


Form PTO-1595 (Rev. 07/05)
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RECORDATION FORM COVER SHEET

PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

| | | | |
|--|--|---|--|
| 1. Name of conveying party(ies): FRANK PUSCHNER (10/10/2005), DIETMAR DENGLE (10/14/2005), WOLFGANG SCHINDLER (10/10/2005), AND THOMAS SPOTTL (10/14/2005) Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No | | 2. Name and address of receiving party(ies) Name: <u>Infinion Technologies AG</u> Internal Address: _____ Street Address: _____ <u>St.-Martin-Strasse 53</u> City: <u>Munich</u> State: _____ Country: <u>Germany</u> Zip: <u>81669</u> Additional name(s) & address(es) attached? <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No | |
| 3. Nature of conveyance/Execution Date(s): Execution Date(s): <u>In parentheses after Inventor name</u> <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Security Agreement <input type="checkbox"/> Joint Research Agreement <input type="checkbox"/> Government Interest Assignment <input type="checkbox"/> Executive Order 9424, Confirmatory License <input type="checkbox"/> Other _____ | | 4. Application or patent number(s): <input type="checkbox"/> This document is being filed together with a new application. A. Patent Application No.(s) <u>11/206,241</u> Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No B. Patent No.(s) | |
| 5. Name and address to whom correspondence concerning document should be mailed: Name: <u>Laura C. Brutman</u> <u>DARBY & DARBY P.C.</u> Internal Address: <u>Atty. Dkt.: 20196/0203242-USO</u> Street Address: <u>P.O. Box 5257</u> City: <u>New York</u> State: <u>NY</u> Zip: <u>10150-5257</u> Phone Number: <u>(212) 527-7664</u> Fax Number: <u>(212) 527-7701</u> Email Address: <u>lbrutman@darbylaw.com</u> | | 6. Total number of applications and patents involved: <u>1</u> 7. Total fee (37 CFR 1.21(h) & 3.41) \$ <u>40.00</u> <input type="checkbox"/> Authorized to be charged by credit card <input checked="" type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Enclosed <input type="checkbox"/> None required (government interest not affecting title) 8. Payment Information a. Credit Card Last 4 Numbers _____ Expiration Date _____ b. Deposit Account Number <u>04-0100</u> Authorized User Name <u>Flynn Barrison</u> | |
| 9. Signature:  _____ Signature <u>Flynn Barrison - 53,970</u> Name of Person Signing Date <u>November 18, 2005</u> Total number of pages including cover sheet, attachments, and documents: <u>10</u> | | | |

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office, facsimile no. (571) 273-0140, on the date shown below.

Dated: _____ Signature: _____ 0

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| RECORDATION FORM COVER SHEET (continued) | |
|---|---|
| Additional Conveying Party(ies)/Execution Date(s) (1. Continued): | |
| Additional Assignees (2. Continued): | |
| Assignee Name: <u>DELO Industire Klebstoffe GmbH & Co. KG</u> | |
| Internal Address: | |
| Street Address: <u>Ohmstrasse 3</u> | |
| City: <u>Landsberg</u> State: _____ Country: <u>Germany</u> Zip: <u>86899</u> | |
| Assignee Name: _____ | |
| Internal Address: | |
| Street Address: | |
| City: _____ State: _____ Country: _____ Zip: _____ | |
| Assignee Name: _____ | |
| Internal Address: | |
| Street Address: | |
| City: _____ State: _____ Country: _____ Zip: _____ | |
| Additional Applications and/or Patents (4. Continued): | |
| Additional Patent Application Numbers 4A. Continued: | Additional Patent Numbers 4B. Continued: |
| Additional numbers attached? <input type="checkbox"/> Yes <input type="checkbox"/> No | |

INFINEON REF NO. _____
O.C. REF NO. 20196/0203242-US0

ASSIGNMENT

For good and valuable consideration, I, Frank Puschner, a citizen of Germany, residing at Kohlenschachtweg 5, 93309 Kelheim, Germany, and I, Dietmar Dengler, a citizen of Germany, residing at H.-v.-Herkomerstrasse 111, 86899 Landsberg, Germany, and I, Wolfgang Schindler, a citizen of Germany, residing at Hauzensteiner Str. 27, 93128 Regensburg, Germany, and I, Thomas Spottl, a citizen of Germany, residing at Bischof-Wittmann-Str. 38, 93051 Regensburg, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Strasse 53, 81669 Munich, Germany, hereinafter "Assignee",

And to **DELO Industrie Klebstoffe GmbH & Co. KG**, a corporation organized and existing under the laws of Germany, having its principal place of business at Ohmstrasse 3, 86899 Landsberg, Germany, hereinafter "Assignee",

its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on: August 16, 2005 US. Serial No. 11/206,241

entitled: **CHIP MODULE**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE:



Name: Frank Puschner

DATE:

October 10th 2005

SIGNATURE:

Name: Dietmar Dengler

DATE:

SIGNATURE:

Name: Wolfgang Schindler

DATE:

SIGNATURE:

Name: Thomas Spottl

DATE:

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SIGNATURE: _____ DATE: _____
Name: Frank Puschner

SIGNATURE: Dietmar Dengler DATE: 14. October 2005
Name: Dietmar Dengler

SIGNATURE: _____ DATE: _____
Name: Wolfgang Schindler

SIGNATURE: _____ DATE: _____
Name: Thomas Spottl

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SIGNATURE: _____ DATE: _____
Name: Frank Puschner

SIGNATURE: _____ DATE: _____
Name: Dietmar Dengler

SIGNATURE: Wolfgang Schindler DATE: 10.10.2005
Name: Wolfgang Schindler

SIGNATURE: _____ DATE: _____
Name: Thomas Spottl

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SIGNATURE: _____ DATE: _____
Name: Frank Puschner

SIGNATURE: _____ DATE: _____
Name: Dietmar Dengler

SIGNATURE: _____ DATE: _____
Name: Wolfgang Schindler

SIGNATURE: Thomas Spottl DATE: 14. Oktober 2005
Name: Thomas Spottl